

**SURFACE MOUNT SCHOTTKY BARRIER DIODE ARRAY**
**Features**

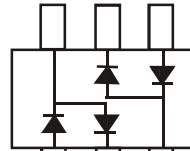
- Low Forward Voltage Drop
- Guard Ring Construction for Transient Protection
- Fast Switching
- Low Reverse Capacitance
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device, (Note 4 and 5)**

**Mechanical Data**

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Polarity: See Diagram
- Leads: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Copper leadframe).
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.016 grams (approximate)



Top View



Device Schematic

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	40	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	28	V
Forward Continuous Current (Note 1)	$I_{FM}$	350	mA
Non-Repetitive Peak Forward Surge Current @ $t \leq 1.0\text{s}$	$I_{FSM}$	1.5	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	$P_D$	225	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	$R_{\theta JA}$	444	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +125	$^\circ\text{C}$

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	40	—	—	V	$I_R = 100\mu\text{A}$
Forward Voltage Drop	$V_F$	—	—	0.37 0.50 0.60	V	$I_F = 20\text{mA}$ $I_F = 100\text{mA}$ $I_F = 200\text{mA}$
Reverse Current (Note 2)	$I_R$	—	—	5.0	$\mu\text{A}$	$V_R = 30\text{V}$
Total Capacitance	$C_T$	—	50	—	pF	$V_R = 0\text{V}, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	10	—	ns	$I_F = I_R = 200\text{mA},$ $I_{rr} = 0.1 \times I_R, R_L = 100\Omega$

- Notes:
1. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. Short duration pulse test used to minimize self-heating effect.
  3. No purposefully added lead.
  4. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

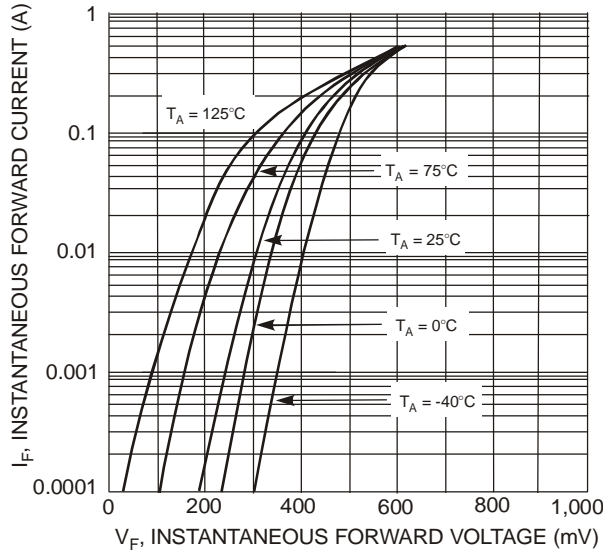


Fig. 1 Typical Forward Characteristics

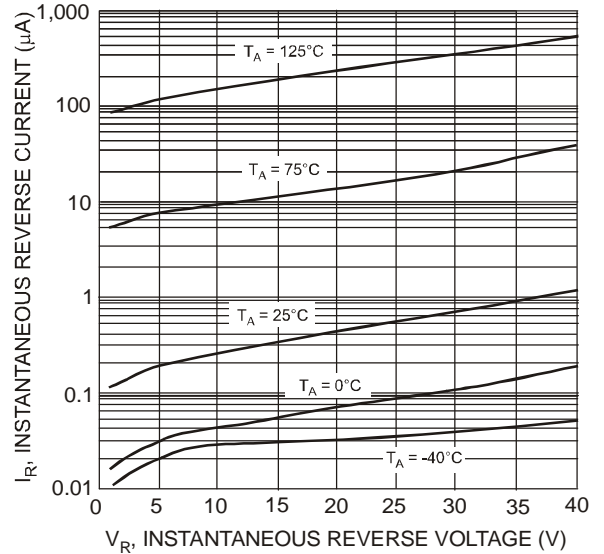


Fig. 2 Typical Reverse Characteristics

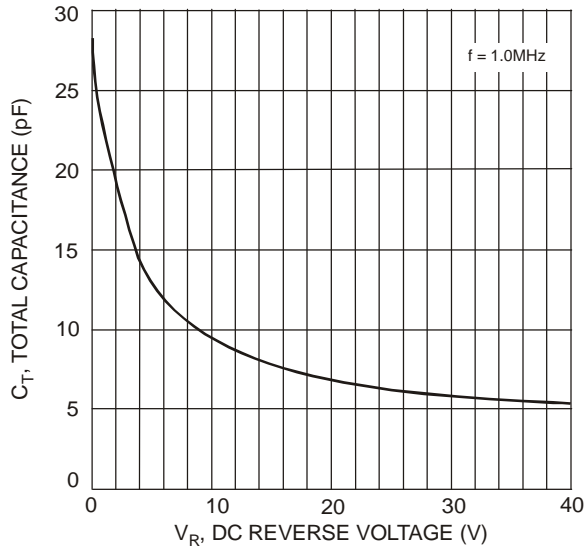


Fig. 3 Total Capacitance vs. Reverse Voltage

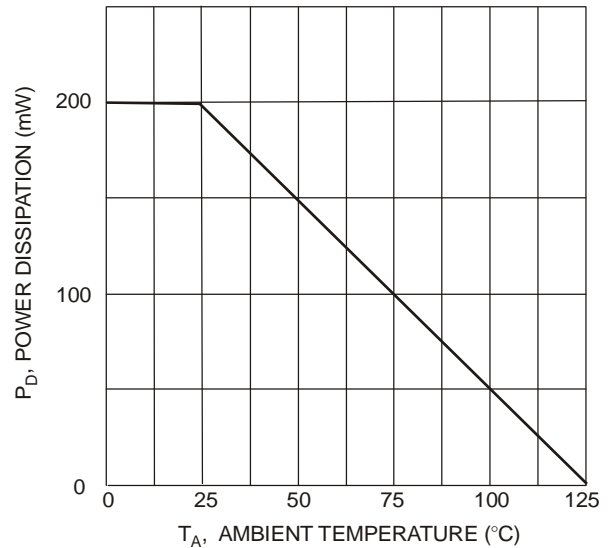


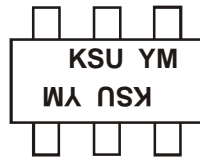
Fig. 4 Power Derating Curve

**Ordering Information** (Notes 5 & 6)

Part Number	Case	Packaging
SD103ASDM-7-F	SOT-26	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**

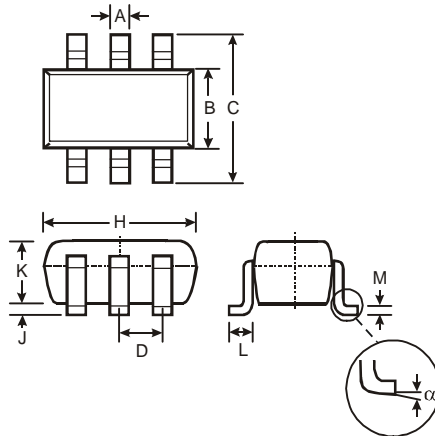


KSU = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: T = 2006)  
 M = Month (ex: 9 = September)

Date Code Key

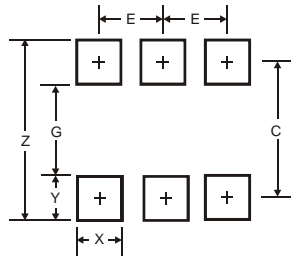
Year	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec		
Code	1	2	3	4	5	6	7	8	9	O	N	D		

**Package Outline Dimensions**



SOT-26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

**Suggested Pad Layout**



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C	2.40
E	0.95

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